Form PTO-1595
To the Honorable Commissioner of Patents

1. Name of conveying party(ies):
Miyako MATSUI

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:
☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other

Execution Date: June 6, 2005

4. Application number(s) or patent number(s):
If this document is being filed together with a new application, the execution date of the application is: June 6, 2005

A. Patent Application No.(s)

B. Patent Registration No.(s)

Additional number(s) attached ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: ANTONELLI, TERRY, STOUT & KRAUS, LLP
Internal Address:
1300 NORTH 17TH STREET – SUITE 1800
City: ARLINGTON State: VA Zip 22209

6. Total number of applications and patents involved ☐

7. Total fee (37 CFR 3.41).............. $40.00
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Melvin Kraus, Reg#22,466
Name of Person Signing

Signature

07/27/2005
Date

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Total number of pages including cover sheet, attachments, and document: ☒

PATENT
REEL: 016822 FRAME: 0391
ASSIGNMENT
(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar ($1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi High-Technologies Corporation, a corporation organized under the laws of Japan, located at 24-14, Nishishinbashii 1-chome, Minato-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi High-Technologies Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

METHOD AND APPARATUS FOR INSPECTING SEMICONDUCTOR DEVICE

Invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi High-Technologies Corporation, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi High-Technologies Corporation,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1) Miyako Matsui

6/6/2005

2)

3)

4)

5)

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RECORDED: 07/27/2005

PATENT
REEL: 016822 FRAME: 0392